Filename: PMP8449\_BOM Date: October 4, 2012

## PMP8449\_BOM

QTY	Referenc	e Value	Description	Size	Part_Number	Manufacture
	1 C8	.1U	Capacitor, Ceramic Chip, 25V, ±10%	603	STD	STD
	1 C5	22p	Capacitor, Ceramic Chip, 50V, ±10%	603		STD
	1 C7	2.2u	Capacitor, Ceramic Chip, 16V, ±10%	805	std	STD
	1 C15	open	Capacitor, Ceramic Chip, xxV, ±10%	805	GRM32ER7YA106KA12L	STD
	1 C9	1u	Capacitor, Ceramic Chip,50V, ±10%	1206		STD
	1 C3	3300p	Capacitor, Ceramic Chip, 630V, ±10%	1206	std	STD
	1 C1	.01u	Capacitor, Leaded, 305 VAC, ±yy%	0.157 x 0.512 inch	B32921C3103M	Epcos
	1 C2	.1u	Capacitor, Leaded, 305 VAC, ±yy%	0.157 x 0.512 inch		Epcos
	1 C6	.1u	Capacitor, Leaded, 305 VAC, ±yy%	0.157 x 0.512 inch	B32921C3104M	Epcos
	1 C10	220pF	CAP CER 220PF 250VAC X1Y2 RAD	7.00 Dia mm		TDK
	1 C4	18U	Capacitor, Aluminum Electrolytic, 35V	0.197 inch		Rubycon
	1 C11	18u	Capacitor, Aluminum Electrolytic, wV	0.248 inch		Rubycon
	1 D2	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	SOT23		Vishay-Liteor
	1 D4	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	SOT23	BAS16	Vishay-Liteor
	1 D7	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	NA	Vishay-Liteor
	1 D6	HD06	Bridge Rectifier, 600V, 0.8A, Glass Passivated, SMD	MINI DIP4		Diodes, Inc
	1 D3	ES1M	Diode, Super Fast Rectifier, 1000V, 1A	0.220 x 0.115 inch	ES1M	Diodes
	1 D5	MBRS3100	Diode, Schottky, 3A, 100V	SMC		Fairchild
	1 L2	1 mH	Inductor, Common Mode Choke, ±30%	10x12 mm		GCI
	1 L1	470 uH	Inductor, SMT, yyA, ± x%	5.80 mm Dia.		Bourns
	1 R24	0	Resistor, Chip, 1/5W, 5%	805	Resistor	Std
	1 R5	100	Resistor, Chip, 1/16W, x%	603	Resistor	Std
	1 R10	10k	Resistor, Chip, 1/8W, 1%	603	Resistor	Std
	1 R9	11.3k	Resistor, Chip, 1/8W, 1%	603	Resistor	Std
	1 R13	51k	Resistor, Chip, 1/8W, 5%	603	Resistor	Std
	1 R8	64.9k	Resistor, Chip, 1/16W, x%	603	Resistor	Std
	1 R25	OPEN	Resistor, Chip, 1/16W, x%	603	Resistor	Std
	1 R1	10k	Resistor, Chip, 1/16W, x%	805	Resistor	Std
	1 R3	49.9	Resistor, Chip, 1/16W, x%	805	Resistor	Std
	1 R14	2	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Resistor	Std
	1 R7	301k	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Resistor	Std
	1 F1	1A	Resistor, Wirewound Lead, 10W, ±5%	0.200 X 0.100 inch	MCRW1A	bussman
	1 R6	301k	Resistor, Chip, 1/4W, 1%	1206	Resistor	Std
	2 R4 R21	75K	Resistor, Chip, 1/4W, 1%	1206	Resistor	Std
	2 R22-23	NA	Resistor, Chip, 1/4W, 5%	1206	Resistor	Std
	3 TP1-3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
	1 TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
	1 U1	TPS92310DGS	IC, Off-Line Primary Side Sensing Controller with PFC	MSOP	TPS92310	TI
	1 Q1	STD4NK80	MOSFET, N-ch, 800V, yy-mA,3.5 Ohms	DPAK	STD4NK80ZT4	STD
	1 T2	2 mH	Transformer, ±10%	16X43 mm		GCI

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